

IN THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) An electronic component comprising:

a board;

a semiconductor device comprising a plurality of first lands formed in a grid and electrically connected to corresponding second lands of a board, said second lands connected to wires formed on the board,

wherein ~~at least one of the~~ a subset of the second lands comprises corresponding to first lands in a corner portion or end portion of the grid each comprise a primary land and an auxiliary land,

each of the at least one subset of second lands connecting connect to at least one of the wires a wire of the board where a predetermined tensile stress is configured to be applied between said at least one second land and said at least one wire,

the primary land comprises an arcuate shape, and

the auxiliary land comprises a first portion disposed adjacent the primary land and a second portion connecting to the ~~at least one~~ wire, the first portion having a greater cross sectional area than the second portion, and

wherein (a) the at least one connecting wire for each land of the subset of second lands comprises a via land, the via land including an arcuate portion electrically connected to a via hole formed in the board outside of the footprint of the grid of the semiconductor device and (b) a predetermined tensile stress is configured to be applied between the subset of second lands and their respective connecting wires.

2. (Previously Presented) The electronic component according to claim 1, wherein said auxiliary land is configured to be disposed where the predetermined tensile stress is applied when a load is applied to said board.

3. (Previously Presented) The electronic component according to claim 2, wherein said auxiliary land electrically connects with at least one of the first lands at a corner of the semiconductor device.

4. (Previously Presented) The electronic component according to claim 2, wherein said auxiliary land electrically connects with at least one of the first lands at an end of an integrated circuit of the semiconductor device.

5. (Previously Presented) The electronic component according to claim 2, wherein said auxiliary land is configured to be disposed so as to extend in a direction in which a warpage of said board is generated.

6. (Previously Presented) The electronic component according to claim 2, wherein said auxiliary land is configured to be disposed where the predetermined tensile stress is applied during correction of a distortion of said board during an assembly of the semiconductor device to the board.

7. (Previously Presented) The electronic component according to claim 2, wherein said auxiliary land comprises a third portion disposed between the first and second portions, the third portion having a cross sectional area less than the first portion and greater than the second portion.

8. (Previously Presented) The electronic component according to claim 3, wherein said auxiliary land has a shape determined based on a position of the auxiliary land in relation to a corner of the semiconductor device.

9. (Previously Presented) The electronic component according to claim 3, wherein said auxiliary land comprises an arcuate shape.

10. (Previously Presented) The electronic component according to claim 2, wherein the at least one second land comprises a second auxiliary land disposed adjacent a through hole.

11.-15. (Canceled)

16. (Currently Amended) An electronic component comprising:

a printed wiring board;

a semiconductor device comprising a plurality of first lands formed in a grid and electrically connected to corresponding second lands of a board, said second lands connected to wires formed on the printed wiring board,

wherein ~~at least one of the~~ a subset of the second lands comprises corresponding to first lands in a corner portion or end portion of the grid each comprise a primary land and an auxiliary land,

~~each of the at least one subset of second lands connects connecting to at least one of the wires~~ a wire of the printed wiring board where a predetermined tensile stress is configured to be applied between said at least one second land and said at least one wire,

the primary land comprises an arcuate shape, and

the auxiliary land comprises a first portion disposed adjacent the primary land and a second portion connecting to the ~~at least one~~ wire, the first portion having a greater cross sectional area than the second portion, and

wherein (a) the ~~at least one~~ connecting wire for each land of the subset of second lands comprises a via land, the via land including an arcuate portion electrically connected to a via hole formed in the printed wiring board outside of the footprint of the grid of the semiconductor device and (b) a predetermined tensile stress is configured to be applied between the subset of second lands and their respective connecting wires.

17. (Currently Amended) An electronic component, comprising:

a semiconductor device having a footprint, and comprising at least one semiconductor land;

a board comprising at least one board land, each of said at least one semiconductor lands electrically connected to a corresponding board land of the at least one semiconductor board lands, the ~~at least one~~ corresponding board lands including a primary portion contacting the at least one semiconductor land and an auxiliary portion electrically connected to a wire,

wherein the primary portion comprises an arcuate shape, and

the auxiliary portion comprises a first portion electrically connected to the primary portion and a second portion electrically connected to the wire, the first portion having a greater cross sectional area than the second portion, and

wherein the wire for each corresponding board land comprises a via land, the via land including an arcuate portion electrically connected to a via hole formed in the board outside of the footprint of the semiconductor device.

18. (Previously Presented) The electronic component according to claim 17, wherein the primary portion comprises a circular shape.

19. (Previously Presented) The electronic component according to claim 17, wherein the auxiliary portion has an about triangular shape.

20. (Previously Presented) The electronic component according to claim 17, wherein the auxiliary portion has a tapered shape.

21. (Previously Presented) The electronic component according to claim 17, wherein the auxiliary portion has a tear drop shape.

22. (Previously Presented) The electronic component according to claim 17, wherein the auxiliary portion has a third portion between the first and second portions, the third portion having a cross sectional area between the cross sectional areas of the first and second portions.